



SLDBS Material Safety Data Sheet

No.	Material Content Declaration					
	Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
1	Lead wire 21.872%	Copper (Cu)	7440-50-8	51.5300	99.9775	384,232.3
		Phosphorus (P)	7723-14-0	0.0005	0.0010	3.8
		Arsenic (As)	7440-38-2	0.0005	0.0010	3.8
		Tin (Sn)	7440-31-5	0.0005	0.0010	3.8
		Oxygen (O)	7782-44-7	0.0003	0.0005	1.9
		Sulfur (S)	7704-34-9	0.0068	0.0132	50.8
		Iron (Fe)	7439-89-6	0.0003	0.0007	2.5
		Nickel (Ni)	7440-02-0	0.0002	0.0003	1.2
		Bismuth (Bi)	7440-69-9	0.0010	0.0020	7.7
		Antimony (Sb)	1309-64-4	0.0010	0.0020	7.7
		Lead (Pb)	7439-92-1	0.0003	0.0005	1.9
		Zinc (Zn)	7440-66-6	0.0002	0.0003	1.2
		Total			51.54	
2	Solder wafer 1.021%	Lead (Pb)	7439-92-1	4.06	92.48	30,273.3
		Tin (Sn)	7440-31-5	0.22	5.01	1,640.4
		Silver (Ag)	7440-22-4	0.11	2.51	820.2
		Total			4.39	
3	Chip 0.84%	Silicon (Si)	7440-21-3	3.16	100.00	23,562.5
		Total			3.16	
4	Molding 76.057%	Silica (SiO ₂)	14808-60-7	55.34	74.11	412,626.1
		Epoxy resin	29690-82-2	12.69	17.00	94,651.8
		Phenolic resin	9003-35-4	6.57	8.80	48,996.2
		Phosphorus(P)	7723-14-0	0.04	0.05	278.4
		Carbon Black	1333-86-4	0.03	0.04	222.7
		Total			74.67	
5	Plating 0.21%	Tin (Sn)	7440-31-5	0.35	100.00	2,609.8
		Total			0.35	
Total mass (mg)			134.11			